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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### **Details**

Product Status	Obsolete
Number of LABs/CLBs	640
Number of Logic Elements/Cells	6400
Total RAM Bits	81920
Number of I/O	175
Number of Gates	404000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	240-BFQFP
Supplier Device Package	240-PQFP (32x32)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep20k160eqc240-2">https://www.e-xfl.com/product-detail/intel/ep20k160eqc240-2</a>

- Flexible clock management circuitry with up to four phase-locked loops (PLLs)
  - Built-in low-skew clock tree
  - Up to eight global clock signals
  - ClockLock® feature reducing clock delay and skew
  - ClockBoost® feature providing clock multiplication and division
  - ClockShift™ programmable clock phase and delay shifting
- Powerful I/O features
  - Compliant with peripheral component interconnect Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2* for 3.3-V operation at 33 or 66 MHz and 32 or 64 bits
  - Support for high-speed external memories, including DDR SDRAM and ZBT SRAM (ZBT is a trademark of Integrated Device Technology, Inc.)
  - Bidirectional I/O performance ( $t_{CO} + t_{SU}$ ) up to 250 MHz
  - LVDS performance up to 840 Mbits per channel
  - Direct connection from I/O pins to local interconnect providing fast  $t_{CO}$  and  $t_{SU}$  times for complex logic
  - MultiVolt I/O interface support to interface with 1.8-V, 2.5-V, 3.3-V, and 5.0-V devices (see [Table 3](#))
  - Programmable clamp to  $V_{CCIO}$
  - Individual tri-state output enable control for each pin
  - Programmable output slew-rate control to reduce switching noise
  - Support for advanced I/O standards, including low-voltage differential signaling (LVDS), LVPECL, PCI-X, AGP, CTT, stub-series terminated logic (SSTL-3 and SSTL-2), Gunning transceiver logic plus (GTL+), and high-speed terminated logic (HSTL Class I)
  - Pull-up on I/O pins before and during configuration
- Advanced interconnect structure
  - Four-level hierarchical FastTrack® Interconnect structure providing fast, predictable interconnect delays
  - Dedicated carry chain that implements arithmetic functions such as fast adders, counters, and comparators (automatically used by software tools and megafunctions)
  - Dedicated cascade chain that implements high-speed, high-fan-in logic functions (automatically used by software tools and megafunctions)
  - Interleaved local interconnect allows one LE to drive 29 other LEs through the fast local interconnect
- Advanced packaging options
  - Available in a variety of packages with 144 to 1,020 pins (see [Tables 4 through 7](#))
  - FineLine BGA® packages maximize board space efficiency
- Advanced software support
  - Software design support and automatic place-and-route provided by the Altera® Quartus® II development system for

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

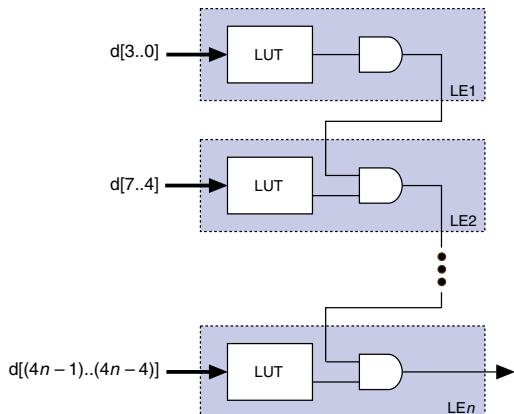
### Cascade Chain

With the cascade chain, the APEX 20K architecture can implement functions with a very wide fan-in. Adjacent LUTs can compute portions of a function in parallel; the cascade chain serially connects the intermediate values. The cascade chain can use a logical AND or logical OR (via De Morgan's inversion) to connect the outputs of adjacent LEs. Each additional LE provides four more inputs to the effective width of a function, with a short cascade delay. Cascade chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry.

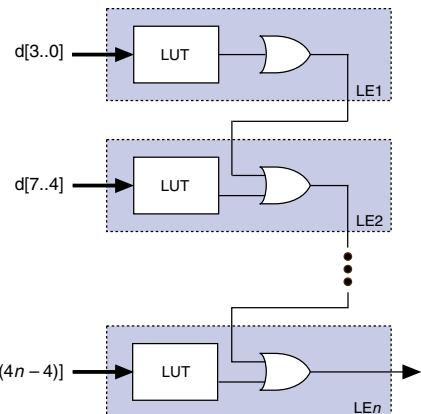
Cascade chains longer than ten LEs are implemented automatically by linking LABs together. For enhanced fitting, a long cascade chain skips alternate LABs in a MegaLAB structure. A cascade chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure. [Figure 7](#) shows how the cascade function can connect adjacent LEs to form functions with a wide fan-in.

**Figure 7. APEX 20K Cascade Chain**

#### AND Cascade Chain



#### OR Cascade Chain



**Table 9. APEX 20K Routing Scheme**

Source	Destination								
	Row I/O Pin	Column I/O Pin	LE	ESB	Local Interconnect	MegaLAB Interconnect	Row FastTrack Interconnect	Column FastTrack Interconnect	FastRow Interconnect
Row I/O Pin					✓	✓	✓	✓	
Column I/O Pin								✓	✓ (1)
LE					✓	✓	✓	✓	
ESB					✓	✓	✓	✓	
Local Interconnect	✓	✓	✓	✓					
MegaLAB Interconnect					✓				
Row FastTrack Interconnect						✓		✓	
Column FastTrack Interconnect						✓	✓		
FastRow Interconnect					✓ (1)				

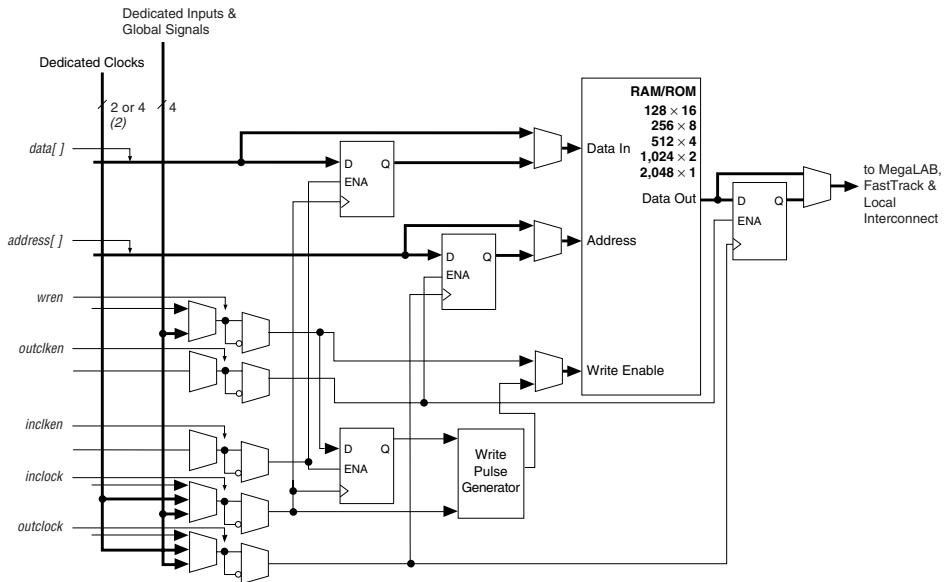
**Note to Table 9:**

(1) This connection is supported in APEX 20KE devices only.

## Product-Term Logic

The product-term portion of the MultiCore architecture is implemented with the ESB. The ESB can be configured to act as a block of macrocells on an ESB-by-ESB basis. Each ESB is fed by 32 inputs from the adjacent local interconnect; therefore, it can be driven by the MegaLAB interconnect or the adjacent LAB. Also, nine ESB macrocells feed back into the ESB through the local interconnect for higher performance. Dedicated clock pins, global signals, and additional inputs from the local interconnect drive the ESB control signals.

In product-term mode, each ESB contains 16 macrocells. Each macrocell consists of two product terms and a programmable register. [Figure 13](#) shows the ESB in product-term mode.

**Figure 22. ESB in Single-Port Mode Note (1)****Notes to Figure 22:**

- (1) All registers can be asynchronously cleared by ESB local interconnect signals, global signals, or the chip-wide reset.
- (2) APEX 20KE devices have four dedicated clocks.

## Content-Addressable Memory

In APEX 20KE devices, the ESB can implement CAM. CAM can be thought of as the inverse of RAM. When read, RAM outputs the data for a given address. Conversely, CAM outputs an address for a given data word. For example, if the data FA12 is stored in address 14, the CAM outputs 14 when FA12 is driven into it.

CAM is used for high-speed search operations. When searching for data within a RAM block, the search is performed serially. Thus, finding a particular data word can take many cycles. CAM searches all addresses in parallel and outputs the address storing a particular word. When a match is found, a match flag is set high. [Figure 23](#) shows the CAM block diagram.

APEX 20KE devices include an enhanced IOE, which drives the FastRow interconnect. The FastRow interconnect connects a column I/O pin directly to the LAB local interconnect within two MegaLAB structures. This feature provides fast setup times for pins that drive high fan-outs with complex logic, such as PCI designs. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The APEX 20KE IOE also includes direct support for open-drain operation, giving faster clock-to-output for open-drain signals. Some programmable delays in the APEX 20KE IOE offer multiple levels of delay to fine-tune setup and hold time requirements. The Quartus II software compiler can set these delays automatically to minimize setup time while providing a zero hold time.

**Table 11** describes the APEX 20KE programmable delays and their logic options in the Quartus II software.

**Table 11. APEX 20KE Programmable Delay Chains**

Programmable Delays	Quartus II Logic Option
Input Pin to Core Delay	Decrease input delay to internal cells
Input Pin to Input Register Delay	Decrease input delay to input registers
Core to Output Register Delay	Decrease input delay to output register
Output Register $t_{CO}$ Delay	Increase delay to output pin
Clock Enable Delay	Increase clock enable delay

The register in the APEX 20KE IOE can be programmed to power-up high or low after configuration is complete. If it is programmed to power-up low, an asynchronous clear can control the register. If it is programmed to power-up high, an asynchronous preset can control the register. [Figure 26](#) shows how fast bidirectional I/O pins are implemented in APEX 20KE devices. This feature is useful for cases where the APEX 20KE device controls an active-low input or another device; it prevents inadvertent activation of the input upon power-up.

The APEX 20K device instruction register length is 10 bits. The APEX 20K device USERCODE register length is 32 bits. [Tables 20](#) and [21](#) show the boundary-scan register length and device IDCODE information for APEX 20K devices.

**Table 20. APEX 20K Boundary-Scan Register Length**

Device	Boundary-Scan Register Length
EP20K30E	420
EP20K60E	624
EP20K100	786
EP20K100E	774
EP20K160E	984
EP20K200	1,176
EP20K200E	1,164
EP20K300E	1,266
EP20K400	1,536
EP20K400E	1,506
EP20K600E	1,806
EP20K1000E	2,190
EP20K1500E	1 ( <a href="#">1</a> )

*Note to Table 20:*

- (1) This device does not support JTAG boundary scan testing.

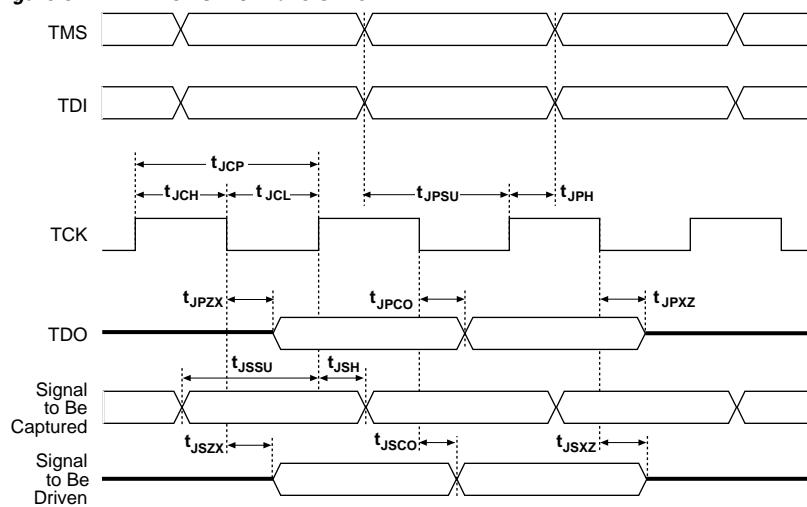
**Table 21. 32-Bit APEX 20K Device IDCODE**

Device	IDCODE (32 Bits) (1)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer Identity (11 Bits)	1 (1 Bit) (2)
EP20K30E	0000	1000 0000 0011 0000	000 0110 1110	1
EP20K60E	0000	1000 0000 0110 0000	000 0110 1110	1
EP20K100	0000	0000 0100 0001 0110	000 0110 1110	1
EP20K100E	0000	1000 0001 0000 0000	000 0110 1110	1
EP20K160E	0000	1000 0001 0110 0000	000 0110 1110	1
EP20K200	0000	0000 1000 0011 0010	000 0110 1110	1
EP20K200E	0000	1000 0010 0000 0000	000 0110 1110	1
EP20K300E	0000	1000 0011 0000 0000	000 0110 1110	1
EP20K400	0000	0001 0110 0110 0100	000 0110 1110	1
EP20K400E	0000	1000 0100 0000 0000	000 0110 1110	1
EP20K600E	0000	1000 0110 0000 0000	000 0110 1110	1
EP20K1000E	0000	1001 0000 0000 0000	000 0110 1110	1

**Notes to Table 21:**

- (1) The most significant bit (MSB) is on the left.
- (2) The IDCODE's least significant bit (LSB) is always 1.

Figure 31 shows the timing requirements for the JTAG signals.

**Figure 31. APEX 20K JTAG Waveforms**

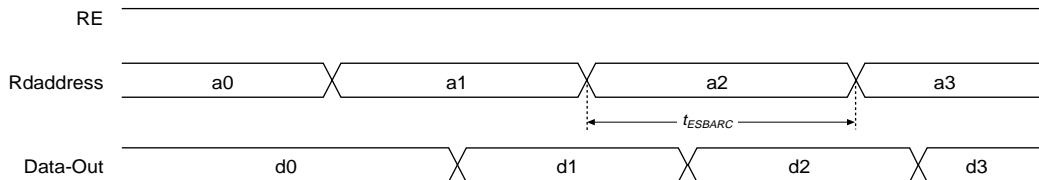
**Table 25. APEX 20K 5.0-V Tolerant Device DC Operating Conditions (Part 2 of 2) Notes (2), (7), (8)**

<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>	<b>Min</b>	<b>Typ</b>	<b>Max</b>	<b>Unit</b>
$V_{OL}$	3.3-V low-level TTL output voltage	$I_{OL} = 12 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (11)			0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ V}$ (11)			0.2	V
	3.3-V low-level PCI output voltage	$I_{OL} = 1.5 \text{ mA DC}$ , $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ (11)			$0.1 \times V_{CCIO}$	V
	2.5-V low-level output voltage	$I_{OL} = 0.1 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (11)			0.2	V
		$I_{OL} = 1 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (11)			0.4	V
		$I_{OL} = 2 \text{ mA DC}$ , $V_{CCIO} = 2.30 \text{ V}$ (11)			0.7	V
$I_I$	Input pin leakage current	$V_I = 5.75 \text{ to } -0.5 \text{ V}$	-10		10	$\mu\text{A}$
$I_{IOZ}$	Tri-stated I/O pin leakage current	$V_O = 5.75 \text{ to } -0.5 \text{ V}$	-10		10	$\mu\text{A}$
$I_{CC0}$	V <sub>CC</sub> supply current (standby) (All ESBs in power-down mode)	$V_I = \text{ground, no load, no}$ toggling inputs, -1 speed grade (12)		10		mA
		$V_I = \text{ground, no load, no}$ toggling inputs, -2, -3 speed grades (12)		5		mA
$R_{CONF}$	Value of I/O pin pull-up resistor before and during configuration	$V_{CCIO} = 3.0 \text{ V}$ (13)	20		50	W
		$V_{CCIO} = 2.375 \text{ V}$ (13)	30		80	W

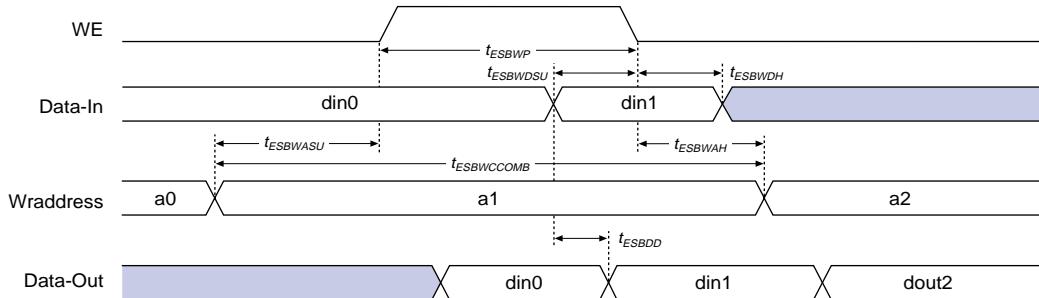
Figures 38 and 39 show the asynchronous and synchronous timing waveforms, respectively, for the ESB macroparameters in Table 31.

**Figure 38. ESB Asynchronous Timing Waveforms**

#### ESB Asynchronous Read



#### ESB Asynchronous Write



**Table 41. EP20K200  $f_{MAX}$  Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Units
	Min	Max	Min	Max	Min	Max	
t <sub>SU</sub>	0.5		0.6		0.8		ns
t <sub>H</sub>	0.7		0.8		1.0		ns
t <sub>CO</sub>		0.3		0.4		0.5	ns
t <sub>LUT</sub>		0.8		1.0		1.3	ns
t <sub>ESBRC</sub>		1.7		2.1		2.4	ns
t <sub>ESBW</sub>		5.7		6.9		8.1	ns
t <sub>ESBWESU</sub>	3.3		3.9		4.6		ns
t <sub>ESBDA</sub>	2.2		2.7		3.1		ns
t <sub>ESBDATAH</sub>	0.6		0.8		0.9		ns
t <sub>ESBADDRS</sub>	2.4		2.9		3.3		ns
t <sub>ESBDATACO1</sub>		1.3		1.6		1.8	ns
t <sub>ESBDATACO2</sub>		2.6		3.1		3.6	ns
t <sub>ESBDD</sub>		2.5		3.3		3.6	ns
t <sub>PD</sub>		2.5		3.0		3.6	ns
t <sub>PTERMSU</sub>	2.3		2.7		3.2		ns
t <sub>PTERMCO</sub>		1.5		1.8		2.1	ns
t <sub>F1-4</sub>		0.5		0.6		0.7	ns
t <sub>F5-20</sub>		1.6		1.7		1.8	ns
t <sub>F20+</sub>		2.2		2.2		2.3	ns
t <sub>CH</sub>	2.0		2.5		3.0		ns
t <sub>CL</sub>	2.0		2.5		3.0		ns
t <sub>CLRP</sub>	0.3		0.4		0.4		ns
t <sub>PREP</sub>	0.4		0.5		0.5		ns
t <sub>ESBCH</sub>	2.0		2.5		3.0		ns
t <sub>ESBCL</sub>	2.0		2.5		3.0		ns
t <sub>ESBWP</sub>	1.6		1.9		2.2		ns
t <sub>ESBRP</sub>	1.0		1.3		1.4		ns

**Table 46. EP20K200 External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub> (1)	1.9		2.3		2.6		ns
t <sub>INHBIDIR</sub> (1)	0.0		0.0		0.0		ns
t <sub>OUTCOBIDIR</sub> (1)	2.0	4.6	2.0	5.6	2.0	6.8	ns
t <sub>XZBIDIR</sub> (1)		5.0		5.9		6.9	ns
t <sub>ZXBIDIR</sub> (1)		5.0		5.9		6.9	ns
t <sub>INSUBIDIR</sub> (2)	1.1		1.2		—		ns
t <sub>INHBIDIR</sub> (2)	0.0		0.0		—		ns
t <sub>OUTCOBIDIR</sub> (2)	0.5	2.7	0.5	3.1	—	—	ns
t <sub>XZBIDIR</sub> (2)		4.3		5.0		—	ns
t <sub>ZXBIDIR</sub> (2)		4.3		5.0		—	ns

**Table 47. EP20K400 External Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSU</sub> (1)	1.4		1.8		2.0		ns
t <sub>INH</sub> (1)	0.0		0.0		0.0		ns
t <sub>OUTCO</sub> (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
t <sub>INSU</sub> (2)	0.4		1.0		—		ns
t <sub>INH</sub> (2)	0.0		0.0		—		ns
t <sub>OUTCO</sub> (2)	0.5	3.1	0.5	4.1	—	—	ns

**Table 48. EP20K400 External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub> (1)	1.4		1.8		2.0		ns
t <sub>INHBIDIR</sub> (1)	0.0		0.0		0.0		ns
t <sub>OUTCOBIDIR</sub> (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
t <sub>XZBIDIR</sub> (1)		7.3		8.9		10.3	ns
t <sub>ZXBIDIR</sub> (1)		7.3		8.9		10.3	ns
t <sub>INSUBIDIR</sub> (2)	0.5		1.0		—		ns
t <sub>INHBIDIR</sub> (2)	0.0		0.0		—		ns
t <sub>OUTCOBIDIR</sub> (2)	0.5	3.1	0.5	4.1	—	—	ns
t <sub>XZBIDIR</sub> (2)		6.2		7.6		—	ns
t <sub>ZXBIDIR</sub> (2)		6.2		7.6		—	ns

**Table 62. EP20K100E  $f_{MAX}$  ESB Timing Microparameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>ESBARC</sub>		1.61		1.84		1.97	ns
t <sub>ESBSRC</sub>		2.57		2.97		3.20	ns
t <sub>ESBAWC</sub>		0.52		4.09		4.39	ns
t <sub>ESBSWC</sub>		3.17		3.78		4.09	ns
t <sub>ESBWASU</sub>	0.56		6.41		0.63		ns
t <sub>ESBWAH</sub>	0.48		0.54		0.55		ns
t <sub>ESBWDSU</sub>	0.71		0.80		0.81		ns
t <sub>ESBWDH</sub>	.048		0.54		0.55		ns
t <sub>ESBRASU</sub>	1.57		1.75		1.87		ns
t <sub>ESBRAH</sub>	0.00		0.00		0.20		ns
t <sub>ESBWESU</sub>	1.54		1.72		1.80		ns
t <sub>ESBWEH</sub>	0.00		0.00		0.00		ns
t <sub>ESBDATASU</sub>	-0.16		-0.20		-0.20		ns
t <sub>ESBDAZH</sub>	0.13		0.13		0.13		ns
t <sub>ESBWADDRSU</sub>	0.12		0.08		0.13		ns
t <sub>ESBRAADDRSU</sub>	0.17		0.15		0.19		ns
t <sub>ESBDAZCO1</sub>		1.20		1.39		1.52	ns
t <sub>ESBDAZCO2</sub>		2.54		2.99		3.22	ns
t <sub>ESBDD</sub>		3.06		3.56		3.85	ns
t <sub>PD</sub>		1.73		2.02		2.20	ns
t <sub>PTERMSU</sub>	1.11		1.26		1.38		ns
t <sub>PTERMCO</sub>		1.19		1.40		1.08	ns

**Table 63. EP20K100E  $f_{MAX}$  Routing Delays**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>F1-4</sub>		0.24		0.27		0.29	ns
t <sub>F5-20</sub>		1.04		1.26		1.52	ns
t <sub>F20+</sub>		1.12		1.36		1.86	ns

**Table 90. EP20K400E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub>	2.93		3.23		3.44		ns
t <sub>INHBIDIR</sub>	0.00		0.00		0.00		ns
t <sub>OUTCOBIDIR</sub>	2.00	5.25	2.00	5.79	2.00	6.32	ns
t <sub>XZBIDIR</sub>		5.95		6.77		7.12	ns
t <sub>ZXBIDIR</sub>		5.95		6.77		7.12	ns
t <sub>INSUBIDIRPLL</sub>	4.31		4.76		-		ns
t <sub>INHBIDIRPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOBIDIRPLL</sub>	0.50	2.25	0.50	2.45	-	-	ns
t <sub>XZBIDIRPLL</sub>		2.94		3.43		-	ns
t <sub>ZXBIDIRPLL</sub>		2.94		3.43		-	ns

Tables 91 through 96 describe  $f_{MAX}$  LE Timing Microparameters,  $f_{MAX}$  ESB Timing Microparameters,  $f_{MAX}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K600E APEX 20KE devices.

**Table 91. EP20K600E  $f_{MAX}$  LE Timing Microparameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>SU</sub>	0.16		0.16		0.17		ns
t <sub>H</sub>	0.29		0.33		0.37		ns
t <sub>CO</sub>		0.65		0.38		0.49	ns
t <sub>LUT</sub>		0.70		1.00		1.30	ns

**Table 92. EP20K600E  $f_{MAX}$  ESB Timing Microparameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{ESBARC}$		1.67		2.39		3.11	ns
$t_{ESBSRC}$		2.27		3.07		3.86	ns
$t_{ESBAWC}$		3.19		4.56		5.93	ns
$t_{ESBSWC}$		3.51		4.62		5.72	ns
$t_{ESBWASU}$	1.46		2.08		2.70		ns
$t_{ESBWAH}$	0.00		0.00		0.00		ns
$t_{ESBWDSU}$	1.60		2.29		2.97		ns
$t_{ESBWDH}$	0.00		0.00		0.00		ns
$t_{ESBRASU}$	1.61		2.30		2.99		ns
$t_{ESBRAH}$	0.00		0.00		0.00		ns
$t_{ESBWESU}$	1.49		2.30		3.11		ns
$t_{ESBWEH}$	0.00		0.00		0.00		ns
$t_{ESBDAVASU}$	-0.01		0.35		0.71		ns
$t_{ESBDAVATAH}$	0.13		0.13		0.13		ns
$t_{ESBWADDRSU}$	0.19		0.62		1.06		ns
$t_{ESBRAADDRSU}$	0.25		0.71		1.17		ns
$t_{ESBDAACO1}$		1.01		1.19		1.37	ns
$t_{ESBDAACO2}$		2.18		3.12		4.05	ns
$t_{ESBDD}$		3.19		4.56		5.93	ns
$t_{PD}$		1.57		2.25		2.92	ns
$t_{PTERMSU}$	0.85		1.43		2.01		ns
$t_{PTERMCO}$		1.03		1.21		1.39	ns

**Table 93. EP20K600E  $f_{MAX}$  Routing Delays**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{F1-4}$		0.22		0.25		0.26	ns
$t_{F5-20}$		1.26		1.39		1.52	ns
$t_{F20+}$		3.51		3.88		4.26	ns

**Table 94. EP20K600E Minimum Pulse Width Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>CH</sub>	2.00		2.50		2.75		ns
t <sub>CL</sub>	2.00		2.50		2.75		ns
t <sub>CLRP</sub>	0.18		0.26		0.34		ns
t <sub>PREP</sub>	0.18		0.26		0.34		ns
t <sub>ESBCH</sub>	2.00		2.50		2.75		ns
t <sub>ESBCL</sub>	2.00		2.50		2.75		ns
t <sub>ESBWP</sub>	1.17		1.68		2.18		ns
t <sub>ESBRP</sub>	0.95		1.35		1.76		ns

**Table 95. EP20K600E External Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSU</sub>	2.74		2.74		2.87		ns
t <sub>INH</sub>	0.00		0.00		0.00		ns
t <sub>OUTCO</sub>	2.00	5.51	2.00	6.06	2.00	6.61	ns
t <sub>INSUPLL</sub>	1.86		1.96		-		ns
t <sub>INHPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOPLL</sub>	0.50	2.62	0.50	2.91	-	-	ns

**Table 96. EP20K600E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub>	0.64		0.98		1.08		ns
t <sub>INHBIDIR</sub>	0.00		0.00		0.00		ns
t <sub>OUTCOBIDIR</sub>	2.00	5.51	2.00	6.06	2.00	6.61	ns
t <sub>XZBIDIR</sub>		6.10		6.74		7.10	ns
t <sub>ZXBIDIR</sub>		6.10		6.74		7.10	ns
t <sub>INSUBIDIRPLL</sub>	2.26		2.68		-		ns
t <sub>INHBIDIRPLL</sub>	0.00		0.00		-		ns
t <sub>OUTCOBIDIRPLL</sub>	0.50	2.62	0.50	2.91	-	-	ns
t <sub>XZBIDIRPLL</sub>		3.21		3.59		-	ns
t <sub>ZXBIDIRPLL</sub>		3.21		3.59		-	ns

Tables 97 through 102 describe  $f_{MAX}$  LE Timing Microparameters,  $f_{MAX}$  ESB Timing Microparameters,  $f_{MAX}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K1000E APEX 20KE devices.

**Table 97. EP20K1000E  $f_{MAX}$  LE Timing Microparameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>SU</sub>	0.25		0.25		0.25		ns
t <sub>H</sub>	0.25		0.25		0.25		ns
t <sub>CO</sub>		0.28		0.32		0.33	ns
t <sub>LUT</sub>		0.80		0.95		1.13	ns

**Table 102. EP20K1000E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub>	3.22		3.33		3.51		ns
t <sub>INHBDIR</sub>	0.00		0.00		0.00		ns
t <sub>OUTCOBIDIR</sub>	2.00	5.75	2.00	6.33	2.00	6.90	ns
t <sub>XZBIDIR</sub>		6.31		7.09		7.76	ns
t <sub>ZXBIDIR</sub>		6.31		7.09		7.76	ns
t <sub>INSUBIDIRPLL</sub>	3.25		3.26				ns
t <sub>INHBDIRPLL</sub>	0.00		0.00				ns
t <sub>OUTCOBIDIRPLL</sub>	0.50	2.25	0.50	2.99			ns
t <sub>XZBIDIRPLL</sub>		2.81		3.80			ns
t <sub>ZXBIDIRPLL</sub>		2.81		3.80			ns

Tables 103 through 108 describe  $f_{MAX}$  LE Timing Microparameters,  $f_{MAX}$  ESB Timing Microparameters,  $f_{MAX}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K1500E APEX 20KE devices.

**Table 103. EP20K1500E  $f_{MAX}$  LE Timing Microparameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>SU</sub>	0.25		0.25		0.25		ns
t <sub>H</sub>	0.25		0.25		0.25		ns
t <sub>CO</sub>		0.28		0.32		0.33	ns
t <sub>LUT</sub>		0.80		0.95		1.13	ns

**Table 108. EP20K1500E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub>	3.47		3.68		3.99		ns
t <sub>INHBIDIR</sub>	0.00		0.00		0.00		ns
t <sub>OUTCOBIDIR</sub>	2.00	6.18	2.00	6.81	2.00	7.36	ns
t <sub>XZBIDIR</sub>		6.91		7.62		8.38	ns
t <sub>ZXBIDIR</sub>		6.91		7.62		8.38	ns
t <sub>INSUBIDIRPLL</sub>	3.05		3.26				ns
t <sub>INHBIDIRPLL</sub>	0.00		0.00				ns
t <sub>OUTCOBIDIRPLL</sub>	0.50	2.67	0.50	2.99			ns
t <sub>XZBIDIRPLL</sub>		3.41		3.80			ns
t <sub>ZXBIDIRPLL</sub>		3.41		3.80			ns

Tables 109 and 110 show selectable I/O standard input and output delays for APEX 20KE devices. If you select an I/O standard input or output delay other than LVCMOS, add or subtract the selected speed grade to or from the LVCMOS value.

**Table 109. Selectable I/O Standard Input Delays**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
LVCMOS		0.00		0.00		0.00	ns
LVTTL		0.00		0.00		0.00	ns
2.5 V		0.00		0.04		0.05	ns
1.8 V		-0.11		0.03		0.04	ns
PCI		0.01		0.09		0.10	ns
GTL+		-0.24		-0.23		-0.19	ns
SSTL-3 Class I		-0.32		-0.21		-0.47	ns
SSTL-3 Class II		-0.08		0.03		-0.23	ns
SSTL-2 Class I		-0.17		-0.06		-0.32	ns
SSTL-2 Class II		-0.16		-0.05		-0.31	ns
LVDS		-0.12		-0.12		-0.12	ns
CTT		0.00		0.00		0.00	ns
AGP		0.00		0.00		0.00	ns

SRAM configuration elements allow APEX 20K devices to be reconfigured in-circuit by loading new configuration data into the device. Real-time reconfiguration is performed by forcing the device into command mode with a device pin, loading different configuration data, reinitializing the device, and resuming user-mode operation. In-field upgrades can be performed by distributing new configuration files.

## Configuration Schemes

The configuration data for an APEX 20K device can be loaded with one of five configuration schemes (see [Table 111](#)), chosen on the basis of the target application. An EPC2 or EPC16 configuration device, intelligent controller, or the JTAG port can be used to control the configuration of an APEX 20K device. When a configuration device is used, the system can configure automatically at system power-up.

Multiple APEX 20K devices can be configured in any of five configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

**Table 111. Data Sources for Configuration**

Configuration Scheme	Data Source
Configuration device	EPC1, EPC2, EPC16 configuration devices
Passive serial (PS)	MasterBlaster or ByteBlasterMV download cable or serial data source
Passive parallel asynchronous (PPA)	Parallel data source
Passive parallel synchronous (PPS)	Parallel data source
JTAG	MasterBlaster or ByteBlasterMV download cable or a microprocessor with a JAM or JBC File



For more information on configuration, see *Application Note 116 (Configuring APEX 20K, FLEX 10K, & FLEX 6000 Devices.)*

## Device Pin-Outs

See the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information